



1733

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**PATENT**

Applicant: Kuo-Chuan LIU, et al.

Serial No.: 10/066,485

Filed: February 1, 2002

For: METHOD FOR JOINING  
CONDUCTIVE STRUCTURES  
AND AN ELECTRICAL  
CONDUCTIVE ARTICLE

Art Unit: 1733

Examiner: John T. HARAN

Atty Dkt.: 6136/53592 (25916-125)

**CERTIFICATE OF  
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(37 C.F.R. § 1.8(a))**

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Jordan Wilson

**RESPONSE TO RESTRICTION REQUIREMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Restriction Requirement mailed by the U.S. Patent and Trademark Office (USPTO) on October 22, 2003, Applicant elects Group I, Claims 1 – 3 and 5 – 18, *with traverse*.

Applicant traverses the restriction because the examiner's premise in favor of the restriction is in error. Specifically, the examiner states, as to claim 4: "The product as claimed can be made by ... a process that does not involve transforming the thin bonding layer." However, this statement is directly contradicted by Claim 4 which requires that the thin bonding layer is "formed from a bonding layer precursor having a melting temperature substantially lower than the bonding-layer melting temperature." Thus, contrary to the examiner's statement, the claim *specifically* requires that there be a transformation of a bonding layer precursor. Thus, the examiner has failed to make the requisite showing that the inventions are distinct.

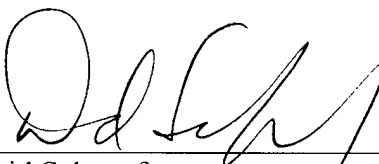
As required by the examiner, in view of the election of Group I, Applicant further elects the species of claims 5 – 15 *with traverse*. Applicant agrees with the examiner that claims 1 – 3 are

generic. However, the examiner contends that there are two disclosed species as follows: (1) claims 5 – 15, wherein a bonding layer is first deposited on a conducting structure (such as a pad) before being joined to a post, and (2) claims 16 – 18, wherein the bonding layer is first deposited on a post before being joined to a conducting structure (such as a pad). Thus, in the context of the present invention the difference between these two “species” is whether the bonding layer is first placed on the post or on the pad. In both cases the post and the pad are thereafter joined in the identical way. Given all of the teachings of the present application it is not material whether the thin bonding layer is first placed on the pad or on the post. *This is not an admission that these claims should be construed the same way vis-à-vis the prior art.* Applicant makes no admission beyond how the claims relate to each other in view of the totality of the teachings of the present patent application.

November 12, 2003

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Respectfully submitted,

  
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